Characteristics CPL-WB-02D3

1 Characteristics

Table 1. Absolute maximum rating (limiting values)

Symbol	Parameter		Value			
			Тур.	Max.	Unit	
P _{IN}	Input power RF _{IN}			25	dBm	
V _{ESD (HBM)}	Human body model, JESD22-A114-B, All I/O	2			kV	
V _{ESD (MM)}	Machine model, JESD22-A115-A, All I/O	100			V	
V _{ESD (CDM)}	Charge device model, JESD22-C101-C, All I/O	500			V	
T _{OP}	Operating temperature			+85	ºC	

Table 2. Electrical characteristics ($T_{amb} = 25 \, ^{\circ}C$) - impedances

Symbol	Parameter		Value		
Symbol			Тур.	Max.	- Unit
Z _{OUT}	Nominal output impedance		50		Ω
Z _{IN}	Nominal input impedance		50		Ω
Z _{CPLD}	Nominal coupling impedance		50		Ω

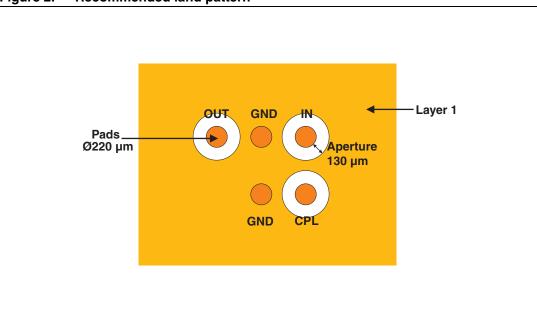
Table 3. Electrical characteristics ($T_{amb} = 25$ °C) - RF performance

Symbol	Parameter	Test condition	Value			Unit
		rest condition		Тур.	Max.	O.III
T _{OP}	Operating temperature		-30		+85	°C
f	Frequency range (bandwidth)		2400		5850	MHz
ΙL	Insertion loss in bandwidth	From 2400 MHz to 2500 MHz			0.2	dB
		From 4900 MHz to 5850 MHz			0.5	
R _L	Return loss in bandwidth (IN, OUT pins)	From 2400 MHz to 5850 MHz	15			dB
CPLD	Coupling factor	From 2400 MHz to 2500 MHz	17	18	19	dB
CITED		From 4900 MHz to 5850 MHz	11	12	13	dB

CPL-WB-02D3 PCB recommendation

2 PCB recommendation

Figure 2. Recommended land pattern



Package information CPL-WB-02D3

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 3. Package dimensions

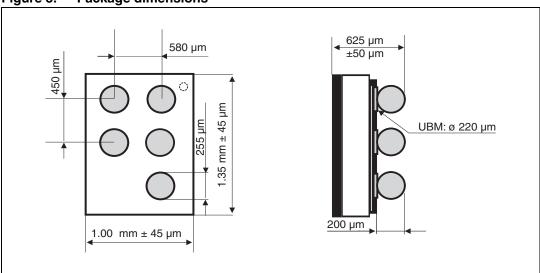


Figure 4. Footprint

Copper pad diameter:
220 µm recommended
260 µm maximum

Solder mask opening:
300 µm minimum

Solder stencil opening:
220 µm recommended

Solder stencil opening:
220 µm recommended

Solder stencil opening:
220 µm recommended

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CPL-WB-02D3 Package information

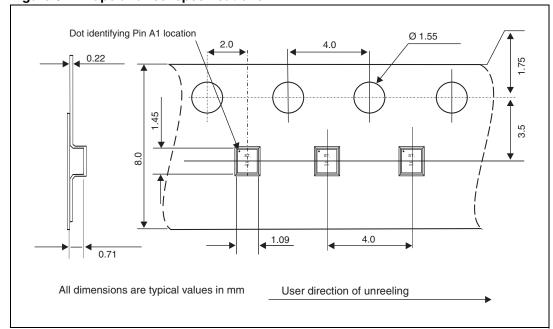


Figure 6. Tape and reel specifications

Note: More information is available in the STMicroelectronics Application note:

AN2348, "IPAD™ 400 µm Flip Chip: package description and recommendations for use" AN1751: "EMI Filters: recommendations and measurements"

Ordering information CPL-WB-02D3

4 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
CPL-WB-02D3	SE	Flip Chip	1.59 mg	5000	Tape and reel

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
18-Jun-2012	1	Initial release

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